

HVU300B

Variable Capacitance Diode for VHF tuner

REJ03G0106-0100Z

(Previous: ADE-208-408)

Rev.1.00

Sep.29.2003

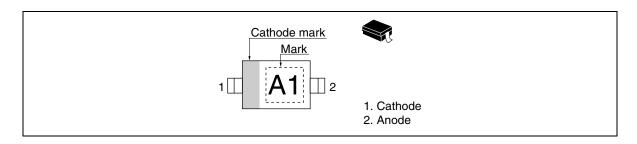
Features

- Low matching error. ($\Delta C/C = 2.0\%$ max)
- High capacitance ratio. (n = 17.0 min)
- Low series resistance. (rs = $1.1 \Omega \text{ max}$)
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVU300B	A1	URP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM} *1	35	V
Reverse voltage	V _R	34	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. $R_L = 10 \text{ k}\Omega$

Electrical Characteristics

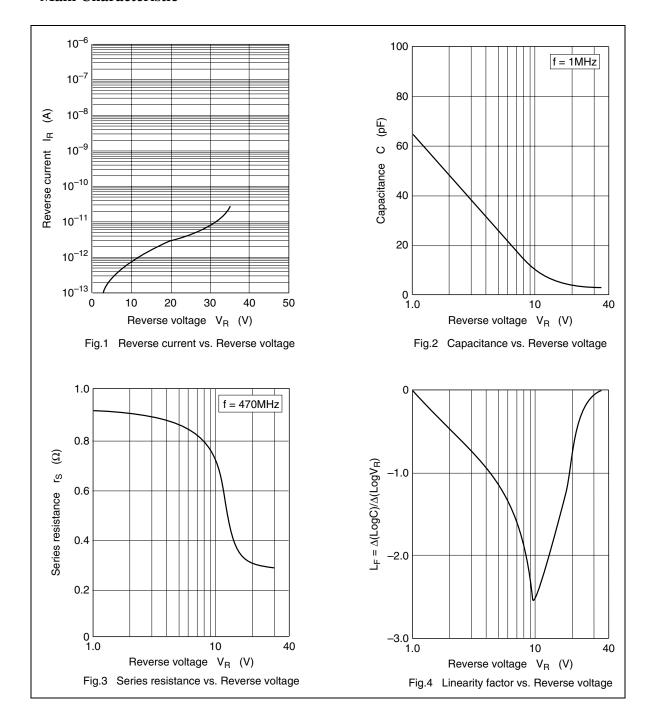
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 32 V
	I _{R2}	_	_	100		V _R = 32 V, Ta = 60°C
Capacitance	C ₂	47.0	_	53.0	pF	V _R = 2 V, f = 1 MHz
	C ₂₅	2.65	_	3.00		V _R = 25 V, f = 1 MHz
Capacitance ratio	n	17.0	_	_	_	C ₂ /C ₂₅
Series resistance	r _s	_	_	1.1	Ω	V _R = 5 V, f = 470 MHz
Matching error	ΔC/C *1	_	_	2.0	%	V _R = 2 to 25 V, f = 1 MHz

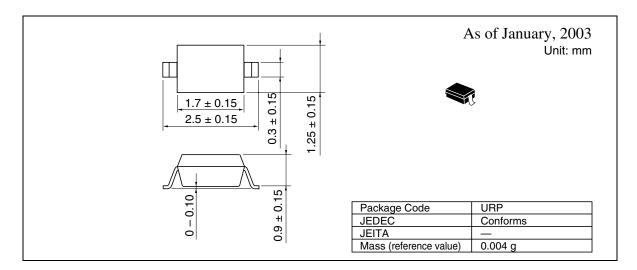
Note: 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of Δ C/C continuous in a reel , expect extention to another group. Calculate Matching Error,

$$\Delta C/C = \frac{(Cmax - Cmin)}{Cmin} \times 100 \text{ (\%)}$$

Main Characteristic



Package Dimensions



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